- **Operating Voltage Range of 4.5 V to 5.5 V**
- **State-of-the-Art BiCMOS Design Significantly Reduces I_{CCZ}**
- **Full Parallel Access for Loading**

- **3-State Outputs Drive Bus Lines or Buffer Memory Address Registers**
- **ESD Protection Exceeds JESD 22**
  - **2000-V Human-Body Model (A114-A)**

SN54BCT373 . . . J OR W PACKAGE
SN74BCT373 . . . DB, DW, N, OR NS PACKAGE
(TOP VIEW)

$\overline{OE}$	1		20	V_{CC}
1Q	2		19	8Q
1D	3		18	8D
2D	4		17	7D
2Q	5		16	7Q
3Q	6		15	6Q
3D	7		14	6D
4D	8		13	5D
4Q	9		12	5Q
GND	10		11	LE
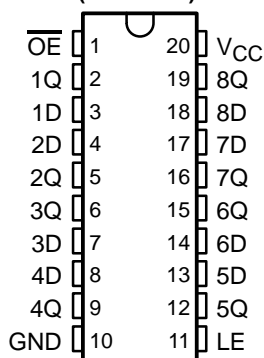
SN54BCT373 . . . FK PACKAGE
(TOP VIEW)

Top pins (left to right): 1D(3), 1Q(2), $\overline{OE}$(1), V_{CC}(20), 8Q(19)

Left side: 2D(4), 2Q(5), 3Q(6), 3D(7), 4D(8)

Right side: 8D(18), 7D(17), 7Q(16), 6Q(15), 6D(14)

Bottom pins (left to right): 4Q(9), GND(10), LE(11), 5Q(12), 5D(13)
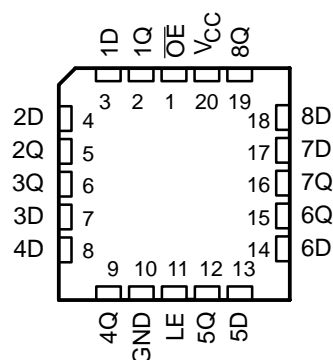
description/ordering information

These 8-bit latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight latches of the 'BCT373 devices are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When the latch enable is taken low, the Q outputs are latched at the logic levels that were set up at the D inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP – N	Tube	SN74BCT373N	SN74BCT373N
	SOIC – DW	Tube	SN74BCT373DW	BCT373
		Tape and reel	SN74BCT373DWR	
	SOP – NS	Tape and reel	SN74BCT373NSR	BCT373
	SSOP – DB	Tape and reel	SN74BCT373DBR	BT373
−55°C to 125°C	CDIP – J	Tube	SNJ54BCT373J	SNJ54BCT373J
	CFP – W	Tube	SNJ54BCT373W	SNJ54BCT373W
	LCCC – FK	Tube	SNJ54BCT373FK	SNJ54BCT373FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

TEXAS INSTRUMENTS

description/ordering information (continued)

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

$\overline{OE}$ does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

FUNCTION TABLE
(each latch)

INPUTS			OUTPUT
$\overline{OE}$	LE	D	Q
L	H	H	H
L	H	L	L
L	L	X	Q_0
H	X	X	Z

logic diagram (positive logic)
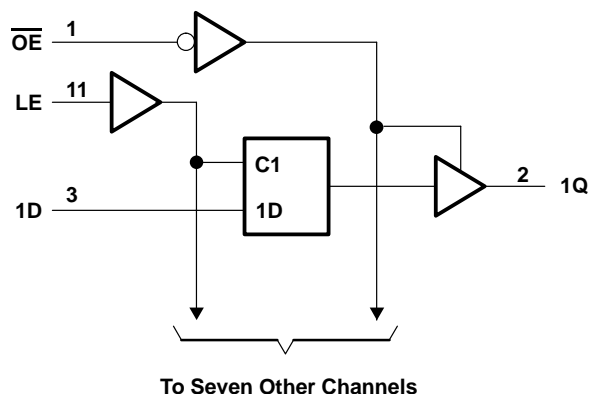
To Seven Other Channels

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} .... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) .... −0.5 V to 7 V
Voltage range applied to any output in the disabled or power-off state, V_O .... −0.5 V to 5.5 V
Voltage range applied to any output in the high state, V_O .... −0.5 V to V_{CC}
Input clamp current, I_{IK} .... −30 mA
Current into any output in the low state: SN54BCT373 .... 96 mA
                                                        SN74BCT373 .... 128 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package .... 70°C/W
                                                                    DW package .... 58°C/W
                                                                    N package .... 69°C/W
                                                                    NS package .... 60°C/W
Storage temperature range, T_{stg} .... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
              2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		SN54BCT373			SN74BCT373			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{IK}	Input clamp current			−18			−18	mA
I_{OH}	High-level output current			−12			−15	mA
I_{OL}	Low-level output current			48			64	mA
T_A	Operating free-air temperature	−55		125	0		70	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54BCT373			SN74BCT373			UNIT
			MIN	TYP[†]	MAX	MIN	TYP[†]	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = −18 mA			−1.2			−1.2	V
V_{OH}	V_{CC} = 4.5 V	I_{OH} = −3 mA	2.4	3.3		2.4	3.3		V
		I_{OH} = −12 mA	2	3.2					
		I_{OH} = −15 mA				2	3.1		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 48 mA		0.38	0.55				V
		I_{OL} = 64 mA					0.42	0.55	
I_I	V_{CC} = 5.5 V,	V_I = 5.5 V			0.4			0.4	mA
I_{IH}	V_{CC} = 5.5 V,	V_I = 2.7 V			20			20	µA
I_{IL}	V_{CC} = 5.5 V,	V_I = 0.5 V			−0.6			−0.6	mA
I_{OS}[‡]	V_{CC} = 5.5 V,	V_O = 0	−100		−225	−100		−225	mA
I_{OZH}	V_{CC} = 5.5 V,	V_O = 2.7 V			50			50	µA
I_{OZL}	V_{CC} = 5.5 V,	V_O = 0.5 V			−50			−50	µA
I_{CCL}	V_{CC} = 5.5 V			37	60		37	60	mA
I_{CCH}	V_{CC} = 5.5 V			2	5		2	5	mA
I_{CCZ}	V_{CC} = 5.5 V			5	8		5	8	mA
C_i	V_{CC} = 5 V,	V_I = 2.5 V or 0.5 V		6			6		pF
C_o	V_{CC} = 5 V,	V_O = 2.5 V or 0.5 V		11			11		pF

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.
[‡] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

		V_{CC} = 5 V, T_A = 25°C		SN54BCT373		SN74BCT373		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, LE high	7.5		7.5		7.5		ns
t_{su}	Setup time, data before LE↓	2		2		2		ns
t_h	Hold time, data after LE↓	5.5		5.5		5.5		ns

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, C_L = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T_A = 25°C			V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T_A = MIN to MAX†				UNIT
			'BCT373			SN54BCT373		SN74BCT373		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	Q	2	5.9	7.7	1.5	10.1	2	9.3	ns
t_{PHL}			2	6.7	8.5	1	10.3	1.5	9.5	
t_{PLH}	LE	Q	2	6.2	8.2	2	10.1	2	9.3	ns
t_{PHL}			2	5.9	7.8	2	9.2	2	8.8	
t_{PZH}	$\overline{OE}$	Q	1	7.8	9.6	1	12.3	1	11.8	ns
t_{PZL}			1	8.2	10.2	1	12.5	1	12	
t_{PHZ}	$\overline{OE}$	Q	1	4.9	6.6	1	7.4	1	7	ns
t_{PLZ}			1	5	6.7	1	8.1	1	7.4	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

TEXAS INSTRUMENTS

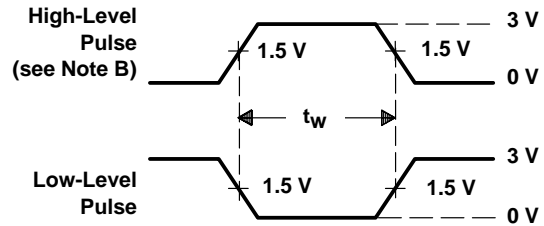## PARAMETER MEASUREMENT INFORMATION
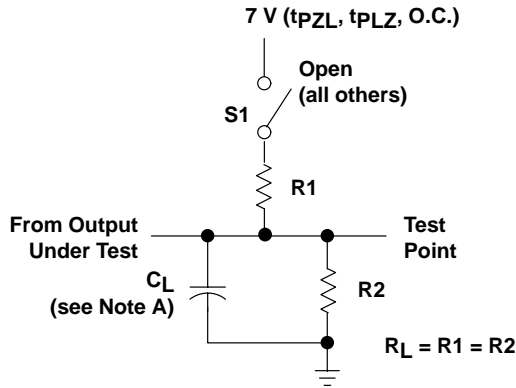
LOAD CIRCUIT FOR
3-STATE AND OPEN-COLLECTOR OUTPUTS
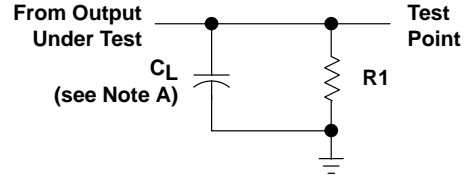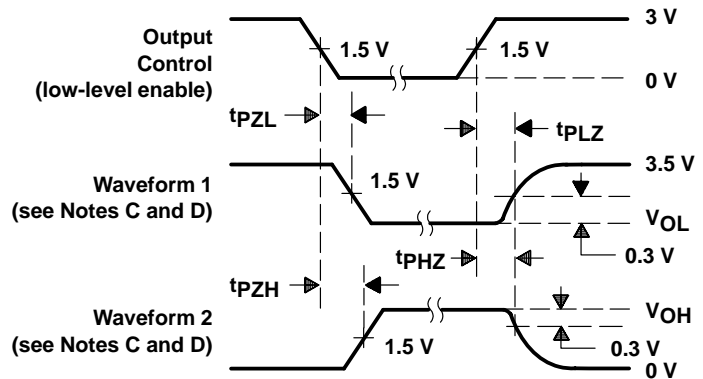
LOAD CIRCUIT FOR
TOTEM-POLE OUTPUTS
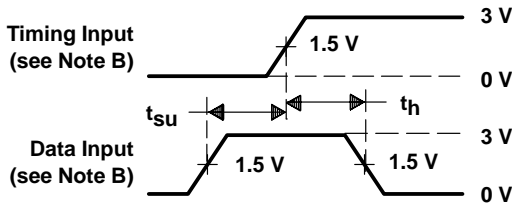
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES

VOLTAGE WAVEFORMS
PULSE DURATION
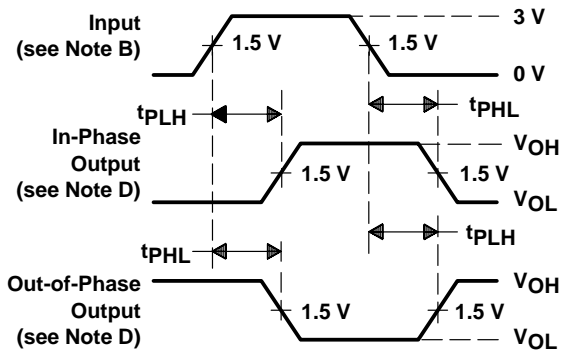
VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES (see Note D)

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

NOTES: A. C_L includes probe and jig capacitance.
 B. All input pulses are supplied by generators having the following characteristics: PRR $\leq$ 10 MHz, t_r = t_f $\leq$ 2.5 ns, duty cycle = 50%.
 C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
  Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 D. The outputs are measured one at a time with one transition per measurement.
 E. When measuring propagation delay times of 3-state outputs, switch S1 is open.
 F. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9074601M2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-9074601M2A SNJ54BCT373FK	Samples
5962-9074601MRA	ACTIVE	CDIP	J	20	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-9074601MRA SNJ54BCT373J	Samples
SNJ54BCT373FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-9074601M2A SNJ54BCT373FK	Samples
SNJ54BCT373J	ACTIVE	CDIP	J	20	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-9074601MRA SNJ54BCT373J	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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FK (S−CQCC−N**)   LEADLESS CERAMIC CHIP CARRIER
28 TERMINAL SHOWN

NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)

4040140/D 01/11

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         C.   This package can be hermetically sealed with a metal lid.
         D.   Falls within JEDEC MS−004

J (R—GDIP—T**)   CERAMIC DUAL IN—LINE PACKAGE
14 LEADS SHOWN

PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

4040083/F 03/03

NOTES: A.   All linear dimensions are in inches (millimeters).
          B.   This drawing is subject to change without notice.
          C.   This package is hermetically sealed with a ceramic lid using glass frit.
          D.   Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
          E.   Falls within MIL STD 1835 GDIP1—T14, GDIP1—T16, GDIP1—T18 and GDIP1—T20.

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